Docket No.: GR 98 P 4137 P

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By:

Date: March 13, 2001

TED STATES PATENT AND TRADEMARK OFFICE

Applicant

Hans-Jürgen Hacke et al.

Appl. No.

09/761,594

Filed

January 16, 2001

Title

Semiconductor Device in Chip Format and Method for

Producing It

CLAIM FOR PRIORITY

Hon. Commissioner of Patents and Trademarks, Washington, D.C. 20231

Sir:

Claim is hereby made for a right of priority under Title 35, U.S. Code, Section 119, based upon the German Patent Application 198 32 706.4 filed July 14, 1998.

A certified copy of the above-mentioned foreign patent application is being submitted herewith.

Respectfully submitted,

D. 40,719

Date: March 13, 2001

Lerner and Greenberg, P.A.

Post Office Box 2480

Hollywood, FL 33022-2480

Tel:

(954) 925-1100

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/mjb



BUNDESREPUBLIK DEUTSCHLAND



Prioritätsbescheinigung über die Einreichung einer Patentanmeldung

Aktenzeichen:

198 32 706.4

Anmeldetag:

14. Juli 1998

Anmelder/Inhaber:

Siemens AG, München/DE

Bezeichnung:

Halbleiterbauelement im Chip-Format

und Verfahren zu seiner Herstellung

IPC:

H 01 L 23/538

Die angehefteten Stücke sind eine richtige und genaue Wiedergabe der ursprünglichen Unterlagen dieser Patentanmeldung.

München, den 13. Februar 2001

Deutsches Patent- und Markenamt

Der Präsident

Im Auftrag

MARKETT MARKET

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OLL SA JOHN MAN

Docket No.: GR 98 P 4137 D

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Bv:

Date:

October 19, 2005

WITHE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No.

10/937,418

Confirmation No: 9046

JFW

Applicant

Hans-Jürgen Hacke, et al.

Filed

September 9, 2004

Art Unit

: 3762

Examiner

Terri L. Smith

Title

Method for Producing a Semiconductor Device in a

Chip Format

Docket No.

GR 98 P 4137 D

Customer No.

24131

Date of Notice of Allowance

: July 19, 2005

LETTER

Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Sir:

Please note that the German Priority document number 198 32 706.4 dated July 14, 1998 was filed on March 15, 2001 in the U.S Patent Office. Please find enclosed copies of the following:

- 4 1) Claim for Priority
 - 2) The cover page of priority document; and
 - 3) The return postcard indicating receipt by the PTO.

Respectfully submitted,

Relph E. Løcher Reg. No. 41,947

Date: October 19, 2005 Lerner and Greenberg, P.A. Post Office Box 2480

Hollywood, FL 33022-2480

Tel: (954) 925-1100 Fax: (954) 925-1101

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March.13;2001 [ail	sidered the date on which	le 53c Prov. / Rule 53d CPA	fm. Ethating Certif.	Cover Sheet WOS.	CIT	3 3 PAT		To the last of the		-		
DOCKET NO. GR. 98P. 41.37. P Mailed March .13, .2001	In e stamp of the Patent Office hereon may be considered the date on which papers indicated below were received.	Applic pgs Rule 53b New Contin Div CIP \ CIP \ \ \ Rule 53c Prov. \ \ \ \ \ Rule 53d CPA \	□ CIPpgs □ TM □ Design □Dwgs □ inf. □ fm/ B Making Certif.	Thriority Claim D'Cert. Prior. Doc(s) PCT Cover Sheet WOS.	☐ Amend pgs ☐ Prel. Amend pgs [☑ Letter	☐ Response pgs ☐ 37CFR1.116 ☐ Not. of Appeal	☐ Brief pgs ☐ Appndx pgs ☐ I.D.S. + Refs.	Assoc Pwr of Atty Specimen L Declaration	□ Pet. for Ext Mo. □ Pet [Check \$ /30	□ Issue Fee □ Assignment ☐ PTOL / ≤ 3.3.	☐ St. of Use ☐ Cert. of Corr. ☐ File rec. corr	

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